

# ST2329

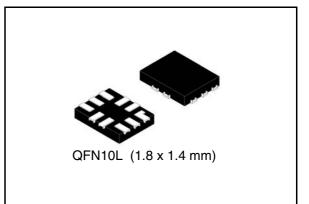
### 2-bit dual supply level translator without direction control pin

#### Features

- 90 Mbps (max) data rate when driven by a totem pole driver
- 8 Mbps (max) data rate when driven by an open drain pole driver
- Bidirectional level translation without direction control pin
- Wide V<sub>L</sub> voltage range of 1.65 to 3.6 V
- Wide V<sub>CC</sub> voltage range of 1.80 to 5.5 V
- Power down mode feature when either supply is off, all I/Os are in high impedance
- Low quiescent current (max 12 µA)
- Able to be driven by totem pole and open drain drivers
- 5.5 V tolerant enable pin
- ESD performance on all pins: ±2 kV HBM
- Small package and footprint QFN10L (1.8 x 1.4 mm) package

### Applications

- Low voltage system level translation
- Mobile phones and other mobile devices
- I<sup>2</sup>C level translation
- UART level translation



### Description

The ST2329 is a 2-bit dual supply level translator which provides the level shifting capability to allow data transfer in a multi-voltage system. Externally applied voltages,  $V_{CC}$  and  $V_L$ , set the logic levels on either side of the device. It utilizes transmission gate-based design that allows bidirectional level translation without a control pin.

The ST2329 accepts a V<sub>L</sub> from 1.65 to 3.6 V and V<sub>CC</sub> from 1.80 to 5.5 V, making it ideal for data transfer between low-voltage ASICs/PLD and higher voltage systems. This device has a tri-state output mode which can be used to disable all I/Os.

The ST2329 supports power down mode when  $V_{CC}$  is grounded/floating and the device is disabled via the OE pin.

#### Table 1. Device summary

Order code	Package	Packaging
ST2329QTR	QFN10L (1.8 x 1.4 mm)	Tape and reel (3000 parts per reel)

## Contents

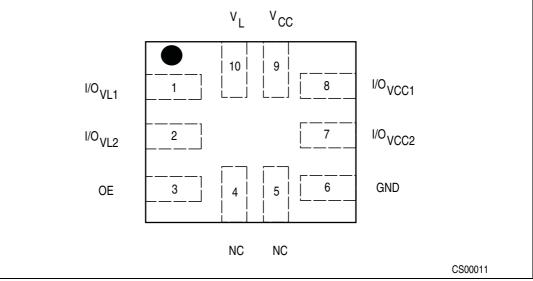
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## 1 Pin settings

#### 1.1 Pin connection

#### Figure 1. Pin connection (top through view)



## 1.2 Pin description

Pin number	Symbol	Name and function
1	I/O <sub>VL1</sub>	Data input/output
2	I/O <sub>VL2</sub>	Data input/output
3	OE	Output enable
4	NC	No connection
5	NC	No connection
6	GND	Ground
7	I/O <sub>VCC2</sub>	Data input/output
8	I/O <sub>VCC1</sub>	Data input/output
9	V <sub>CC</sub>	Supply voltage
10	VL	Supply voltage

#### Table 2. Pin description



## 2 Device block diagrams



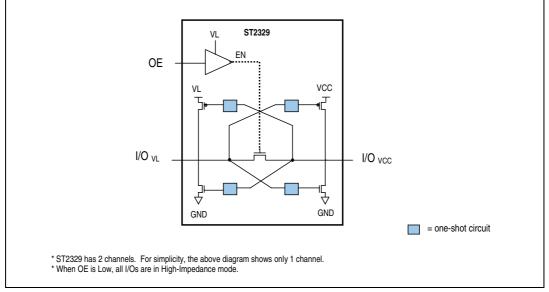
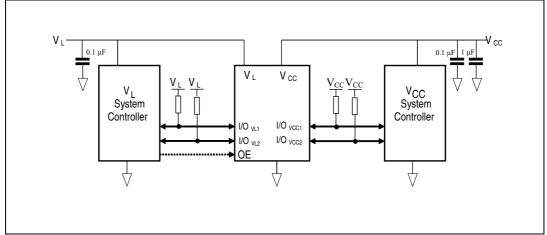


Figure 3. Application block diagram





### 3 Supplementary notes

#### 3.1 Driver requirement

The ST2329 may be driven by an open drain or totem pole driver and the nature of the device's output is "open drain". It must not be used to drive a pull-down resistor since the impedance of the output at HIGH state depends on the pull-up resistor placed at the I/Os.

As the device has pull-up resistors on both the I/O<sub>VCC</sub> and I/O<sub>VL</sub> ports, the user needs to ensure that the driver is able to sink the required amount of current. For example, if the settings are V<sub>CC</sub> = 5.5 V, V<sub>L</sub> = 4.3 V and the pull-up resistor is 10 kΩ then the driver must be able to sink at least (5.5 V/10 kΩ) + (4.3 V /10 kΩ) = 1 mA and still meet the V<sub>IL</sub> requirements of the ST2329.

### 3.2 Load driving capability

To support the open drain system, the one-shot transistor is turned on only during state transition at the output side. When it drives a high state, after the one-shot transistor is turned off, only the pull-up resistor is able to maintain the state. In this case, the resistive load is not recommended.

During the translation from  $V_{CC}$  side to  $V_L$  side, the oscillation might be triggered when the signal is reflected back as a glitch. This is caused by the architecture of the device (auto-direction).

When using the ST2329, care need to be taken in the PCB data-track design and output loading. It is recommended that the load is less than 25 pf.

#### 3.3 Power off feature

In some applications where it might be required to turn off one of the power supplies powering up the level translator, the user may turn off the V<sub>CC</sub> only when the OE pin is low (device is disabled). There will be no current consumption in V<sub>L</sub> due to floating gates or other causes, and the I/Os are in a high-impedance state in this mode.

### 3.4 Truth table

Enable	Bidirectional I	nput/Output
OE	I/O <sub>VCC</sub>	I/O <sub>VL</sub>
H <sup>(1)</sup>	H <sup>(2)</sup>	H <sup>(1)</sup>
H <sup>(1)</sup>	L	L
L	Z <sup>(3)</sup>	Z <sup>(3)</sup>

#### Table 3. Truth table

1. High level V<sub>L</sub> power supply referred

2. High level V<sub>CC</sub> power supply referred

3. Z = high impedance



## 4 Maximum rating

Stressing the device above the rating listed in the "Absolute maximum ratings" table may cause permanent damage to the device. These are stress ratings only, and operation of the device at these or any other conditions above those indicated in the operating sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Refer also to the STMicroelectronics SURE Program and other relevant quality documents.

Symbol	Parameter	Value	Unit
VL	Supply voltage	-0.3 to 4.6	V
V <sub>CC</sub>	Supply voltage	-0.3 to 6.5	V
V <sub>OE</sub>	DC control input voltage	-0.3 to 6.5	V
V <sub>I/OVL</sub>	DC I/O <sub>VL</sub> input voltage (OE = GND or $V_L$ )	-0.3 to V <sub>L</sub> + 0.3	V
V <sub>I/OVCC</sub>	DC I/O <sub>VCC</sub> input voltage (OE = GND or $V_L$ )	-0.3 to V <sub>CC</sub> + 0.3	V
I <sub>IK</sub>	DC input diode current	-20	mA
I <sub>I/OVL</sub>	DC output current	±25	mA
I <sub>I/OVCC</sub>	DC output current	±258	mA
I <sub>SCTOUT</sub>	Short circuit duration, continuous	40	mA
PD	Power dissipation <sup>(1)</sup>	500	mW
T <sub>STG</sub>	Storage temperature	-65 to 150	°C
TL	Lead temperature (10 seconds)	300	°C
ESD	Electrostatic discharge protection (HBM)	±2	kV

Table 4. Absolute maximum ratings

1. 500mW: 65  $^{o}\text{C}$  derated to 300 mW by 10W/ $^{o}\text{C}$ : 65  $^{o}\text{C}$  to 85  $^{o}\text{C}$ 

#### 4.1 Recommended operating conditions

#### Table 5. Recommended operating conditions

Symbol	Parameter	Min	Тур	Max	Unit
VL	Supply voltage	1.65		3.6	V
V <sub>CC</sub> <sup>(1)</sup>	Supply voltage	1.8		5.5	V
V <sub>OE</sub>	Input voltage (OE output enable pin, V <sub>L</sub> power supply referred)	0		3.6	V
VI/O <sub>VL</sub>	I/O <sub>VL</sub> voltage	0		$V_L$	V
V <sub>I</sub> /O <sub>VCC</sub>	I/O <sub>VCC</sub> voltage	0		V <sub>CC</sub>	V
T <sub>op</sub>	Operating temperature	-40		85	°C
dt/dV	Input rise and fall time (for 45 Mbps operation)	0		1	ns/V

1.  $V_{CC}$  must be greater than  $V_L$ .



## 5 Electrical characteristics

Table 6.	DC characteristics (over recommended operating conditions unless otherwise noted. All
	typical values are at $T_A = 25 \text{ °C}$ )

			Test cor	ditions			Value								
Symbol	Parameter				ТА	= 25 °C	;	-40 to 8	85 °C	Unit					
		VL	v <sub>cc</sub>		Min	Тур	Мах	Min	Max						
		1.65			1.4			1.4							
		2.0			1.6			1.6							
V <sub>IHL</sub>	High level input voltage (I/O <sub>VL</sub> )	2.5	$V_L$ to 5.5		2.0			2.0		V					
		3.0			2.4			2.4							
		3.6			2.8			2.8							
		1.65					0.3		0.3						
		2.0					0.4		0.4						
V <sub>ILL</sub>	Low level input voltage (I/O <sub>VL</sub> )	2.5	$V_L$ to 5.5				0.5		0.5	V					
		3.0					0.6		0.6						
		3.6					0.8		0.8						
			1.8		1.6			1.6		v					
		1.0510	2.5		2.3			2.3							
V	High level input voltage (I/O <sub>VCC</sub> )		3.0		2.7			2.7							
V <sub>IHC</sub>		(I/O <sub>VCC</sub> )	$V_{CC}$	3.6		3.3			3.3						
			4.3		3.5			3.5							
			5.5		4.2			4.2							
	Low level input	1.65 - 2.5	3 - 5.5					0.3		V					
V <sub>ILC</sub>	voltage (I/O <sub>VCC</sub> )	2.7 - 3.6	3.6 - 5.5					0.5		V					
		1.65			1.0			1.0							
		2.0			1.2			1.2							
V <sub>IH-OE</sub>	High level input voltage (OE)	2.5	$V_L$ to 5.5		1.4			1.4		V					
	10.1.2g0 (0 _)	3.0			1.6			1.6							
		3.6			2.0			2.0							
		1.65					0.33		0.33						
		2.0					0.40		0.40						
V <sub>IL-OE</sub>	Low level input voltage (OE)	2.5	$V_L$ to 5.5				0.50		0.50	V					
		3.0					0.60		0.60						
		3.6					0.75		0.75						



Table 6.DC characteristics (over recommended operating conditions unless otherwise noted. All<br/>typical values are at  $T_A = 25$  °C) (continued)

			Test cor	ditions	Value					Unit
Symbol	Parameter	v	V	v		TA = 25 °C			5 °C	
		VL	v <sub>cc</sub>		Min	Тур	Max	Min	Max	
V <sub>OLL</sub>	Low level output voltage (I/O <sub>VL</sub> )	1.65 to 3.6	$V_L$ to 5.5	IO = 1.0  mA $I/O_{VCC} \le 0.15 \text{ V}$			0.40		0.40	v
V <sub>OLC</sub>	Low level output voltage (I/O <sub>VCC</sub> )	1.65 to 3.6	$V_L$ to 5.5	IO = 1.0 mA I/O <sub>VL</sub> ≤ 0.15 V			0.40		0.40	v
I <sub>OE</sub>	Control input leakage current (OE)	1.65 to 3.6	$V_L$ to 5.5	V <sub>OE</sub> = GND or V <sub>L</sub>			±0.1		±0.1	μA
I <sub>IO_LKG</sub>	High impedance leakage current (I/O <sub>VL</sub> , I/O <sub>VCC</sub> )	1.65 to 3.6	$V_L$ to 5.5	OE = GND			±0.1		±0.1	μΑ
Ι <sub>ανсс</sub>	Quiescent supply current V <sub>CC</sub>	1.65 to 3.6	$V_L$ to 5.5	only pull-up resistor connected to I/O		3	5		12	μA
I <sub>QVL</sub>	Quiescent supply current V <sub>L</sub>	1.65 to 3.6	$V_L$ to 5.5	only pull-up resistor connected to I/O		0.01	0.1		1	μA
I <sub>z-vcc</sub>	High impedance quiescent supply current V <sub>CC</sub>	1.65 to 3.6	$V_L$ to 5.5	OE = GND; only pull-up resistor connected to I/O		3	5		12	μΑ
I <sub>Z-VL</sub>	High impedance quiescent supply current V <sub>L</sub>	1.65 to 3.6	$V_L$ to 5.5	OE = GND; only pull-up resistor connected to I/O		0.01	0.1		1	μΑ



### 5.1 AC characteristics (device driven by open drain driver)

Table 7.AC characteristics - test conditions:  $V_L = 1.65 - 1.8 \text{ V}$  (load  $C_L = 15 \text{ pF}$ ;  $R_{up} = 4.7 \text{ k}\Omega$ ;<br/>driver  $t_r = t_f \le 2 \text{ ns}$ ) over temperature range -40 °C to 85 °C

Symbol	Parameter		V <sub>CC</sub> = 1.8 –2.5 V		$V_{\rm CC}$ = 2.7 –3.6 V		V <sub>CC</sub> = 4.3 – 5.5 V		Unit
				Max	Min	Мах	Min	Мах	
t <sub>RVCC</sub>	Rise time I/O <sub>VCC</sub>			80		50		30	ns
t <sub>FVCC</sub>	Fall time I/O <sub>VCC</sub>			3		3		3	ns
t <sub>RVL</sub>	Rise time I/O <sub>VL</sub>			7		6		6	ns
t <sub>FVL</sub>	Fall time I/O <sub>VL</sub>			4		5		5	ns
	Propagation delay time	t <sub>PLH</sub>		5		5		5	ns
t <sub>l/OVL-VCC</sub>	I/O <sub>VL-LH</sub> to I/O <sub>VCC-LH</sub> I/O <sub>VL-HL</sub> to I/O <sub>VCC-HL</sub>	t <sub>PHL</sub>		5		5		5	ns
	Propagation delay time	t <sub>PLH</sub>		5		5		5	ns
<sup>t</sup> I/OVCC-VL	I/O <sub>VCC-LH</sub> to I/O <sub>VL-LH</sub> I/O <sub>VCC-HL</sub> to I/O <sub>VL-LH</sub>	t <sub>PHL</sub>		5		7		7	ns
	Output enable and	En		10		10		10	ns
	disable time			40		40		40	ns
D <sub>R</sub>	Data rate <sup>(1)</sup>			1.6		2.5		4	MHz

Table 8.AC characteristics - test conditions:  $V_L = 2.5 - 2.7 V$  (load  $C_L = 15 pF$ ;  $R_{up} = 4.7 k\Omega$ ; driver<br/> $t_r = t_f \le 2 ns$ ) over temperature range -40 °C to 85 °C

Symbol	Parameter		V <sub>CC</sub> = 2.7	$V_{CC}$ = 2.7 $-3.6$ V		$V_{CC} = 4.3 - 5.5 V$	
Symbol	Farameter	Parameter			Min	Max	Unit
t <sub>RVCC</sub>	Rise time I/O <sub>VCC</sub>			70		40	ns
t <sub>FVCC</sub>	Fall time I/O <sub>VCC</sub>			3		3	ns
t <sub>RVL</sub>	Rise time I/O <sub>VL</sub>			5		5	ns
t <sub>FVL</sub>	Fall time I/O <sub>VL</sub>			3		3	ns
	Propagation delay time	t <sub>PLH</sub>		2		2	ns
<sup>t</sup> I/OVL-VCC	I/O <sub>VL-LH</sub> to I/O <sub>VCC-LH</sub> I/O <sub>VL-HL</sub> to I/O <sub>VCC-HL</sub>	t <sub>PHL</sub>		3		3	ns
tl/OVCC-VL	Propagation delay time	t <sub>PLH</sub>		3		3	ns
	I/O <sub>VCC-LH</sub> to I/O <sub>VL-LH</sub> I/O <sub>VCC-HL</sub> to I/O <sub>VL-LH</sub>	t <sub>PHL</sub>		4		4	ns



Symbol	Parameter	$V_{CC}$ = 2.7 $-3.6$ V		$V_{CC} = 4.$	Unit		
Symbol	Farameter	Min	Мах	Min	Мах	Unit	
t <sub>PZL</sub> t <sub>PZH</sub>	Output enable and	En		6		6	ns
t <sub>PLZ</sub> t <sub>PHZ</sub>	disable time	Dis		40		40	ns
D <sub>R</sub>	Data rate <sup>(1)</sup>			2.5		3.2	MHz

1. The data rate is guaranteed based on the condition that the output I/O signal rise/fall time is less than 15% of the input I/O signal period; the input I/O signal is at 50% duty cycle and the output I/O signal duty cycle deviation not less than 30%.

Table 9.AC characteristics - test conditions:  $V_L = 2.7 - 3.6 \text{ V}$  (load  $C_L = 15 \text{ pF}$ ;  $R_{up} = 4.7 \text{ k}\Omega$ ; driver<br/> $t_r = t_f \le 2 \text{ ns}$ ) over temperature range -40 °C to 85 °C

Symbol	Porometer	Parameter		3 – 5.5 V	Unit
Symbol	Farameter	Min	Max	Unit	
t <sub>RVCC</sub>	Rise time I/O <sub>VCC</sub>			55	ns
t <sub>FVCC</sub>	Fall time I/O <sub>VCC</sub>			3	ns
t <sub>RVL</sub>	Rise time I/O <sub>VL</sub>	Rise time I/O <sub>VL</sub>			ns
<sup>t</sup> FVL	Fall time I/O <sub>VL</sub>		3	ns	
	Propagation delay time	t <sub>PLH</sub>		2	ns
ti/OVL-VCC	t <sub>I/OVL-VCC</sub> I/O <sub>VL-LH</sub> to I/O <sub>VCC-LH</sub> I/O <sub>VL-HL</sub> to I/O <sub>VCC-HL</sub>	t <sub>PHL</sub>		4	ns
	Propagation delay time	t <sub>PLH</sub>		4	ns
ti/OVCC-VL	t <sub>I/OVCC-VL</sub> I/O <sub>VCC-LH</sub> to I/O <sub>VL-LH</sub> I/O <sub>VCC-HL</sub> to I/O <sub>VL-HL</sub>	t <sub>PHL</sub>		4	ns
t <sub>PZL</sub> t <sub>PZH</sub>	Output anable and disable time	En		6	ns
t <sub>PLZ</sub> t <sub>PHZ</sub>				40	ns
D <sub>R</sub>	Data rate <sup>(1)</sup>			2.8	MHz

### 5.2 AC characteristics (device driven by totem pole driver )

Table 10.AC characteristics (test conditions:  $V_L = 1.65 - 1.8$  V (load  $C_L = 15$  pF;  $R_{up} = 10$  kΩ; driver $t_r = t_f \le 2$  ns) over temperature range -40 °C to 85 °C)

Symbol	Symbol Parameter		V <sub>CCB</sub> = 1	.8 – 2.5 V	V <sub>CCB</sub> = 2	.7 – 3.6 V	$V_{CCB} = 4$	.3 – 5.5 V	Unit
Symbol			Min	Max	Min	Max	Min	Мах	Unit
t <sub>RVCC</sub>	Rise time I/O <sub>VCC</sub>			7		3		4	ns
<sup>t</sup> FVCC	Fall time I/O <sub>VCC</sub>			7		3		3	ns
t <sub>RVL</sub>	Rise time I/O <sub>VL</sub>			6		4		5	ns
t <sub>FVL</sub>	Fall time I/O <sub>VL</sub>			4		4		4	ns
tuovu	t <sub>I/OVL</sub> - VCC Propagation delay time I/O <sub>VL-LH</sub> to I/O <sub>VCC-LH</sub> I/O <sub>VL-HL</sub> to I/O <sub>VCC-HL</sub>	t <sub>PLH</sub>		6		5		4	ns
		t <sub>PHL</sub>		5		5		5	ns
tuovoo	Propagation delay time	t <sub>PLH</sub>		6		5		4	ns
ti/ovcc- VL	I/O <sub>VCC-LH</sub> to I/O <sub>VL-LH</sub> I/O <sub>VCC-HL</sub> to I/O <sub>VL-HL</sub>	t <sub>PHL</sub>		4.5		5.2		7	ns
t <sub>PZL</sub> t <sub>PZH</sub>	t <sub>PZL</sub> t <sub>PZH</sub> Output enable and	En		10		10		10	ns
t <sub>PLZ</sub> t <sub>PHZ</sub> disable time		Dis		40		40		40	ns
D <sub>R</sub>	Data rate <sup>(1)</sup>	•		12		32		32	MHz

Table 11.	<b>AC characteristics</b> (test conditions: $V_L = 2.5 - 2.7 \text{ V}$ (load $C_L = 15 \text{ pF}$ ; $R_{up} = 10 \text{ k}\Omega$ ; driver
	$t_r = t_f \leq 2$ ns) over temperature range -40 °C to 85 °C)

Symbol	Symbol Parameter		$V_{CC} = 2.7 - 3.6 V$		V <sub>CC</sub> = 4.	Unit		
Symbol			Min	Мах	Min	Max	Unit	
t <sub>RVCC</sub>	Rise time I/O <sub>VCC</sub>			6		4	ns	
t <sub>FVCC</sub>	Fall time I/O <sub>VCC</sub>			3		3	ns	
t <sub>RVL</sub>	Rise time I/O <sub>VL</sub>			5		5	ns	
t <sub>FVL</sub>	Fall time I/O <sub>VL</sub>			3		3	ns	
	Propagation delay time	t <sub>PLH</sub>		3.5		3		
tl/OVL-VCC	C I/O <sub>VCC-LH</sub> to I/O <sub>VL-LH</sub> I/O <sub>VCC-HL</sub> to I/O <sub>VL-HL</sub>	t <sub>PHL</sub>		4		4	ns	
			t	2.5	2.5		2.1	ns
t <sub>I/OVCC-VL</sub> I/O <sub>VCC-LH</sub> to I	Propagation delay time	t <sub>PLH</sub>	2.0	5	2.1	ns		
	I/O <sub>VCC-HL</sub> to I/O <sub>VL-HL</sub>	tour		4		4	ns	
	VOVCC-HL IO VOVL-HL t <sub>PHL</sub> 4	-			ns			



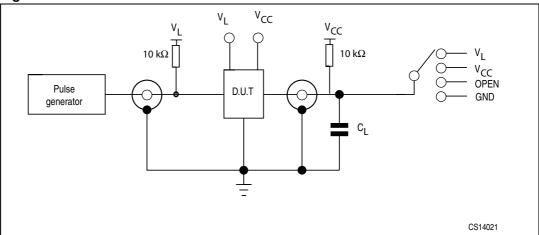
Symbol			$V_{CC} = 2$	.7 –3.6 V	V <sub>CC</sub> = 4.	3 –5.5 V	Unit
Symbol	Parameter -		Min	Max	Min	Max	Unit
t <sub>PZL</sub> t <sub>PZH</sub>	Output enable and	En		6		6	ns
t <sub>PLZ</sub> t <sub>PHZ</sub>	disable time	Dis		40		40	ns
D <sub>R</sub>	Data rate <sup>(1)</sup>			45		45	MHz

1. The data rate is guaranteed based on the condition that the output I/O signal rise/fall time is less than 15% of the input I/O signal period; the input I/O signal is at 50% duty cycle and the output I/O signal duty cycle deviation not less than 30%.

Table 12.	AC characteristics (test conditions: $V_L = 2.7 - 3.6 \text{ V}$ (load $C_L = 15 \text{ pF}$ ; $R_{up} = 10 \text{ k}\Omega$ ; driver
	$t_r = t_f \le 2$ ns) over temperature range -40 °C to 85 °C)

Symbol	Parameter	4.3 –5.5 V	Unit		
Symbol	Symbol Parameter		Min	Мах	- Unit
<sup>t</sup> RVCC	Rise time I/O <sub>VCC</sub>			5	ns
<sup>t</sup> FVCC	Fall time I/O <sub>VCC</sub>			3	ns
t <sub>RVL</sub>	Rise time I/O <sub>VL</sub>			4	ns
t <sub>FVL</sub>	Fall time I/O <sub>VL</sub>			3	ns
	Propagation delay time	t <sub>PLH</sub>		2.5	ns
t <sub>l/OVL-VCC</sub>	t <sub>I/OVL-VCC</sub> I/O <sub>VL-LH</sub> to I/O <sub>VCC-LH</sub> I/O <sub>VL-HL</sub> to I/O <sub>VCC-HL</sub>	t <sub>PHL</sub>		4	ns
				2	ns
<b>t</b>	Propagation delay time			2	ns
<sup>t</sup> I/OVCC-VL	I/O <sub>VCC-LH</sub> to I/O <sub>VL-LH</sub> I/O <sub>VCC-HL</sub> to I/O <sub>VL-HL</sub>			4	ns
		t <sub>PHL</sub>		4	ns
t <sub>PZL</sub> t <sub>PZH</sub>	t <sub>PZL</sub> t <sub>PZH</sub> Output enable and disable t <sub>PLZ</sub> t <sub>PHZ</sub> time	En		6	ns
		Dis		40	ns
D <sub>R</sub>	Data rate <sup>(1)</sup>			45	MHz

#### Figure 4. Test circuit



#### Table 13. Test circuit switches

Tost	Switch				
Test	Driving I/O <sub>VL</sub>	Driving I/O <sub>VCC</sub>	Open drain driving		
t <sub>PLH</sub> , t <sub>PHL</sub>	Open	Open	Open		

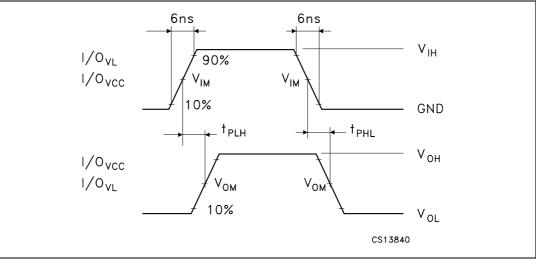


## 6 Waveforms

	Driving	g I/O <sub>VL</sub>	Driving I/O <sub>VCC</sub>		
Symbol	1.8 V $\leq$ V_L $\leq$ V_CC $\leq$ 2.5 V	$\begin{array}{l} \textbf{3.3 V} \leq \textbf{V_L} \leq \textbf{V_{CC}} \leq \\ \textbf{5.0 V} \end{array}$	1.8 V $\leq$ V_L $\leq$ V_CC $\leq$ 2.5 V	$\begin{array}{l} \textbf{3.3V} \leq \textbf{V}_{L} \leq \textbf{V}_{CC} \\ \textbf{5.0 V} \end{array}$	
V <sub>IH</sub>	VL	VL	V <sub>CC</sub>	V <sub>CC</sub>	
V <sub>IM</sub>	50% V <sub>L</sub>	50% V <sub>L</sub>	50% V <sub>CC</sub>	50% V <sub>CC</sub>	
V <sub>OM</sub>	50% V <sub>CC</sub>	50% V <sub>CC</sub>	50% V <sub>L</sub>	50% V <sub>L</sub>	
V <sub>X</sub>	V <sub>OL</sub> +0.15V	V <sub>OL</sub> +0.3V	V <sub>OL</sub> +0.15V	V <sub>OL</sub> +0.3V	
V <sub>Y</sub>	V <sub>OH</sub> -0.15V	V <sub>OH</sub> -0.3V	V <sub>OH</sub> -0.15V	V <sub>OH</sub> -0.3V	

#### Table 14.Waveform symbol value





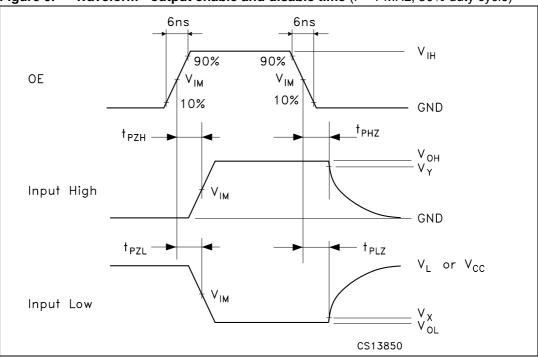


Figure 6. Waveform - output enable and disable time (f = 1 MHz; 50% duty cycle)



## 7 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK<sup>®</sup> packages. These packages have a Lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com.

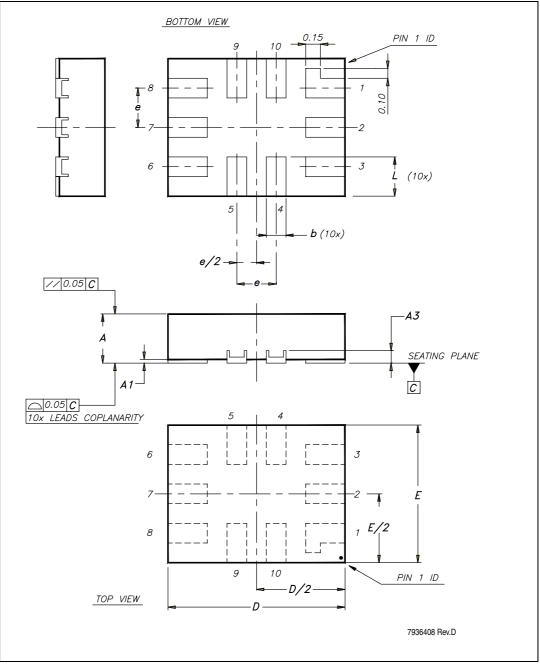


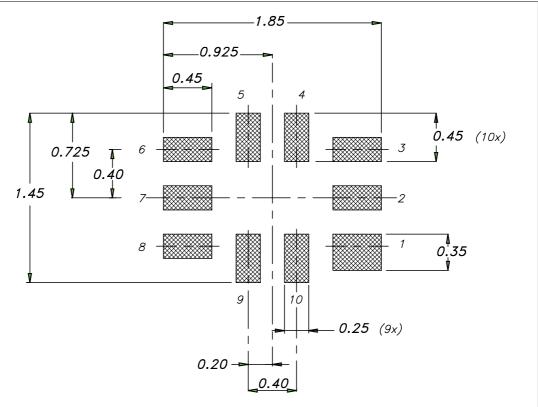
Figure 7. QFN10L (1.8 x 1.4 mm) package outline



Symbol	Millimeters					
	Тур	Min	Мах			
А	0.50	0.45	0.55			
A1	0.02	0	0.05			
A3	0.127					
b	0.20	0.15	0.25			
D	1.80	1.75	1.85			
E	1.40	1.35	1.45			
е	0.40					
L	0.40	0.35	0.45			

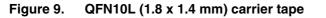
 Table 15.
 QFN10L (1.8 x 1.4 mm) mechanical data





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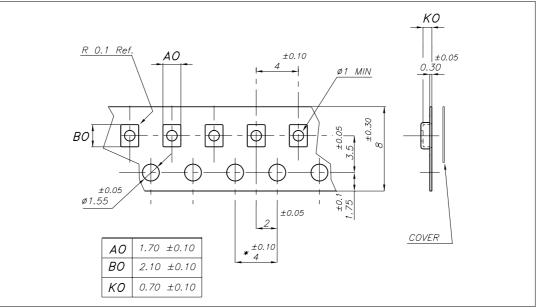
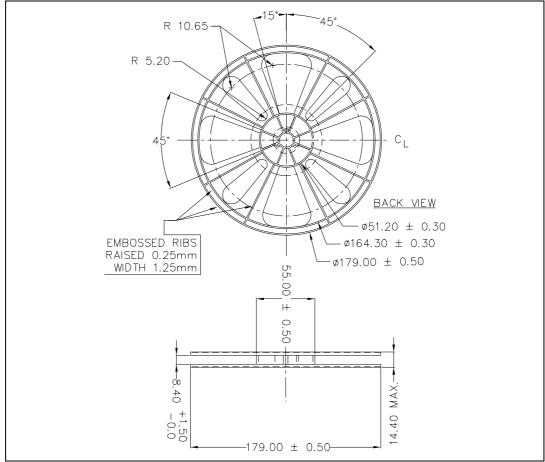


Figure 10. QFN10L (1.8 x 1.4 mm) reel information - back view



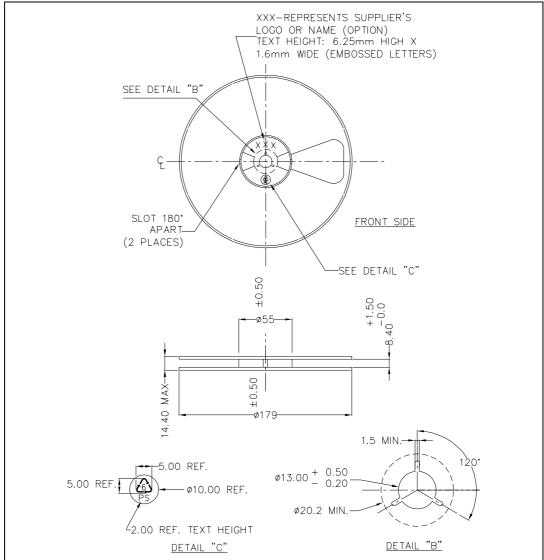


Figure 11. QFN10L (1.8 x 1.4 mm) reel information - front side



## 8 Revision history

Table 16. Doo	ument revision history
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Date	Revision	Changes
15-May-2007	1	Initial release
01-Oct-2007	2	Modified title, added pin description and complete electrical characteristics
31-Oct-2007	3	Updated Figure 4: Test circuit on page 13, Figure 7: QFN10L (1.8 x 1.4 mm) package outline on page 16 and Figure 8: QFN10L (1.8 x 1.4 mm) footprint recommendation on page 17, minor text changes.
07-May-2008	4	Updated data rate values and added paragraph on load driving capability ( <i>Section 3.2</i> ).



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